

DERWENT-ACC-NO: 1980-72052C
DERWENT-WEEK: 198041
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TITLE: Positive photoresist compsn. - comprises halogen substituted alkyl acrylic polymers, for prodn. of integrated circuits and optics

INVENTOR: COUTTET, A; DUBOIS, J C ; ERANIAN, A

PATENT-ASSIGNEE: THOMSON CSF[CSFC]

PRIORITY-DATA: 1979FR-0018467 (July 17, 1979) ,
1979FR-0006136 (March 9, 1979)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
EP 16679 A	October 1, 1980	F
000	N/A	
DE 3060510 G	July 29, 1982	N/A
000	N/A	
EP 16679 B	June 9, 1982	F
000	N/A	
FR 2451050 A	November 7, 1980	N/A
000	N/A	
FR 2461967 A	March 13, 1981	N/A
000	N/A	
JP 55133038 A	October 16, 1980	N/A
000	N/A	
JP 88007377 B	February 16, 1988	N/A
000	N/A	
US 4268590 A	May 19, 1981	N/A
000	N/A	

DESIGNATED-STATES: DE GB IT DE GB IT

CITED-DOCUMENTS: DE 2743763; FR 2299665 ; FR 2339184 ; FR 2389156 ; GB 780218
; US 4061829 ; 2.Jnl.Ref

INT-CL (IPC): C08F220/22; G03C001/72 ; G03F001/00 ;
G03F007/10

ABSTRACTED-PUB-NO: EP 16679A

BASIC-ABSTRACT: Photomask compsn. decomposing when irradiated comprises copolymers of the alpha-alkylacrylic series substd. by ≥ 2 halogen atoms and of formula where the R's are 1-10C alkyl substd. by F, Cl or Br, the indices a, a', b, b', c and c' being integers and are 0 or positive; m, n and p are 0 or positive integers, only one of m, n and p being 0.

The compsn. is used as a positive photoresist and is degradable by electrons, UV (200-300 nm), X-rays (4-50 Angstroms) and gamma-rays. The compsn. exhibits high resolution and is used for the prodn. of integrated circuits and optics.

TITLE-TERMS:

POSITIVE PHOTORESIST COMPOSITION COMPRISE HALOGEN
SUBSTITUTE ALKYL POLYACRYLIC
POLYMER PRODUCE INTEGRATE CIRCUIT OPTICAL

DERWENT-CLASS: A14 A89 G06 L03 P83 P84 U11

CPI-CODES: A04-E; A10-E05; A10-E10; A12-E07A; A12-L02B;
A12-L02E; A12-L03;
G06-D03; G06-D06; G06-F03C; L03-D03B; L03-H04E2;

EPI-CODES: U11-A09;

POLYMER-MULTIPUNCH-CODES-AND-KEY-SERIALS:

Key Serials: 0036 0208 0209 0210 0212 0502 0503 0516 0517
0530 0531 0537 0538
0544 0545 0551 0552 0558 0559 0565 0566 0572 0573 0579 0580
0593 0594 0600 0601
1995 2009 2016 2023 2027 2066 2116 2122 2123 2194 2198 2201
2318 2393 2427 2440
2507 2598 2602 2729 2740 2743 2805 2851 0228 0229 0505 0519
0547 0603 2177 2179
2184 2185 2189 2206 2207
Multipunch Codes: 011 034 045 051 062 063 064 074 077 079
081 082 083 084 085
092 098 145 231 236 246 264 266 27& 28& 316 33- 332 353 355
359 398 402 41- 414
431 445 477 524 541 623 627 628 649 658 679 681 691 722 726

729 011 03& 03- 045
062 063 064 074 077 079 081 083 085 238 239 241 244 250 343
360 58- 723 724

DERWENT-ACC-NO: 1997-532795
DERWENT-WEEK: 199749
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TITLE: Acryloyl:di:methyl:naphthalene compound - is
polymerised to give
light-degradable product for use in packaging or as resist
for fine processing

PATENT-ASSIGNEE: JAPAN ENERGY CORP[NIHA]

PRIORITY-DATA: 1996JP-0065637 (March 22, 1996)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES	MAIN-IPC	
JP 09255726 A	September 30, 1997	N/A
016	C08F 016/36	

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP09255726A	N/A	1996JP-0065637
March 22, 1996		

INT-CL (IPC): B01J027/125; B01J027/135 ; B01J031/02 ;
C07B061/00 ;
C07C045/65 ; C07C049/796 ; C08F016/36

ABSTRACTED-PUB-NO: JP09255726A

BASIC-ABSTRACT: An acryloyldimethylnaphthalene compound of
formula (I) is new.

Also claimed are (1) a halopropionyldimethylnaphthalene
compound of formula
(II) or (III), where X = halogen; (2)
polyacryloyldimethylnapht halene having a
repeat unit of formula (IV) which is prepared by
polymerising compound (I); and
(3) polyacryloyldimethylnaphthalene-methylm ethacrylate
copolymer having a
repeat unit of formula (IV) and (V).

USE - The polymer is suitable as a packaging material or
resist for fine

processing.

ADVANTAGE - The (co)polymer is light-degradable and can form pattern with an electron beam and X-ray or ion beam and has high definition.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS:

ACRYLYL DI METHYL NAPHTHALENE COMPOUND POLYMERISE LIGHT
DEGRADE PRODUCT PACKAGE
RESIST FINE PROCESS

DERWENT-CLASS: A14 A89 A92

CPI-CODES: A04-C; A12-L02E; A12-P01;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1]

018 ; G0373 G0340 G0339 G0260 G0022 D01 D12 D10 D26 D51
D53 D58

D63 F41 F89 D11 D20 D18 D32 D78 D93 ; H0271 ; L9999
L2471 ; L9999

L2131 ; L9999 L2835 ; K9665

Polymer Index [1.2]

018 ; ND08

Polymer Index [1.3]

018 ; C999 C066 C000 ; C999 C259

Polymer Index [1.4]

018 ; R01677 D00 D70 A1 3A C1 7A ; C999 C022 C000 ;
C999 C259

Polymer Index [2.1]

018 ; G0373 G0340 G0339 G0260 G0022 D01 D12 D10 D26 D51
D53 D58

D63 F41 F89 D11 D20 D18 D32 D78 D93 ; H0000 ; H0282 ;
L9999 L2391

; L9999 L2095*R ; M9999 M2095*R ; K9814 K9803 K9790 ;
K9803*R K9790

; K9847*R K9790 ; P0088

Polymer Index [2.2]

018 ; G0373 G0340 G0339 G0260 G0022 D01 D12 D10 D26 D51
D53 D58

D63 F41 F89 D11 D20 D18 D32 D78 D93 ; R00479 G0384
G0339 G0260 G0022

D01 D11 D10 D12 D26 D51 D53 D58 D63 D85 F41 F89 ; H0022
H0011 ;

H0282 ; L9999 L2391 ; L9999 L2095*R ; M9999 M2095*R ;

K9814 K9803

K9790 ; K9803*R K9790 ; K9847*R K9790 ; P0088

Polymer Index [2.3]

018 ; ND04 ; ND09 ; B9999 B3098 B3010 K9847 ; B9999

B4386 B4240

; Q9999 Q8684 Q8673 Q8606 ; Q9999 Q8366*R

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1997-170069